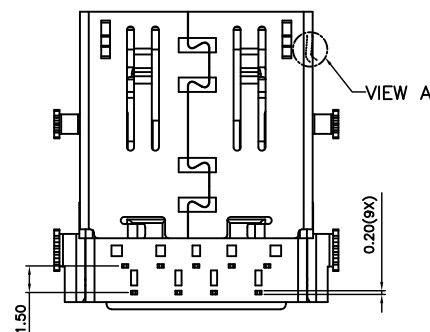
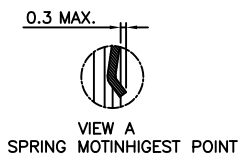
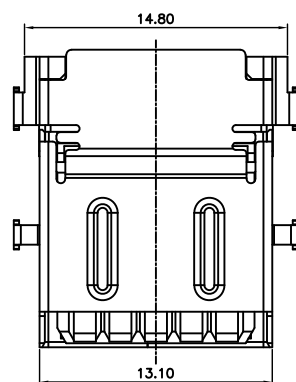
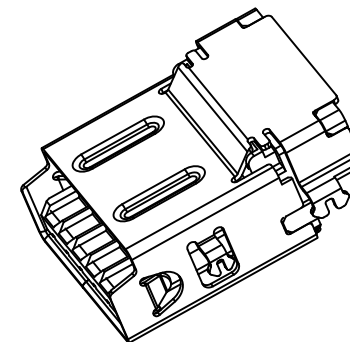
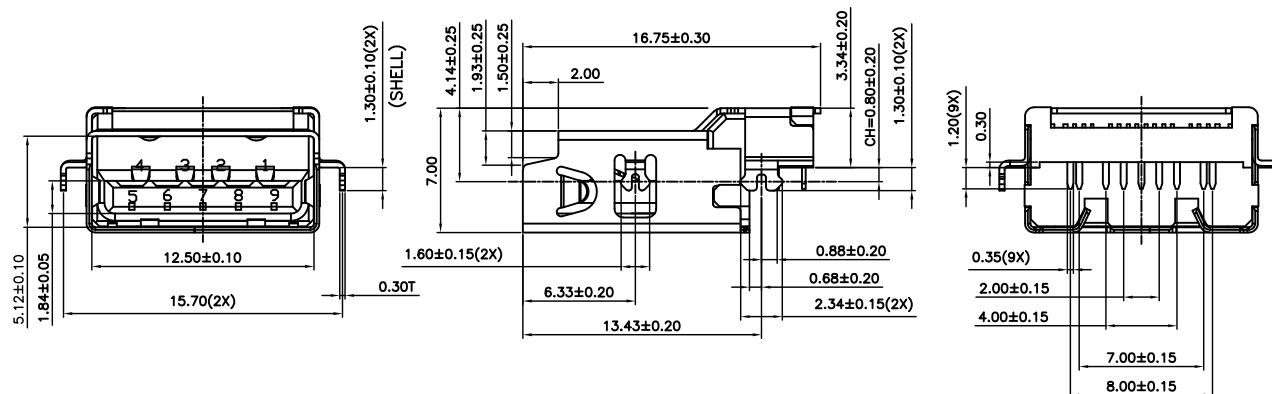




NOTE:

1. MATERIAL :

- 1.1 HOUSING: LCP +30%GF.
1.2 TERMINAL: C2680
1.3 SHELL:SUS

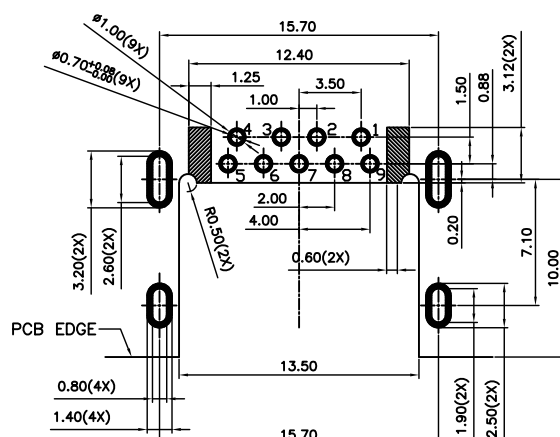
2. PLATING:

- 2.1 TERMINAL: NICKEL 30u" MIN UNDER PLATED OVERALL,
GOLD PLATED ON THE CONTACT AREA.
50u" MATTE Tin ON THE SOLDERING AREA.
2.2 SHELL: NICKEL PLATING OVERALL

3. PART NO. DESCRIPTION:

HYC171-USBA09-080-XX

MATERIAL COLOR
4:LCP 1:BLACK
9:PA9T 2:BLUE



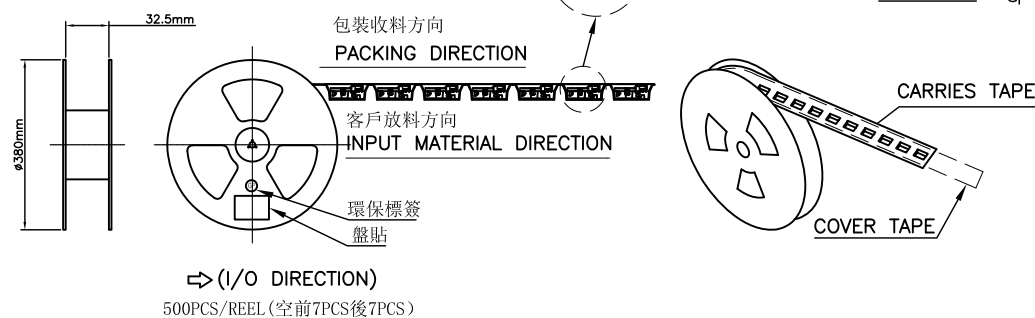
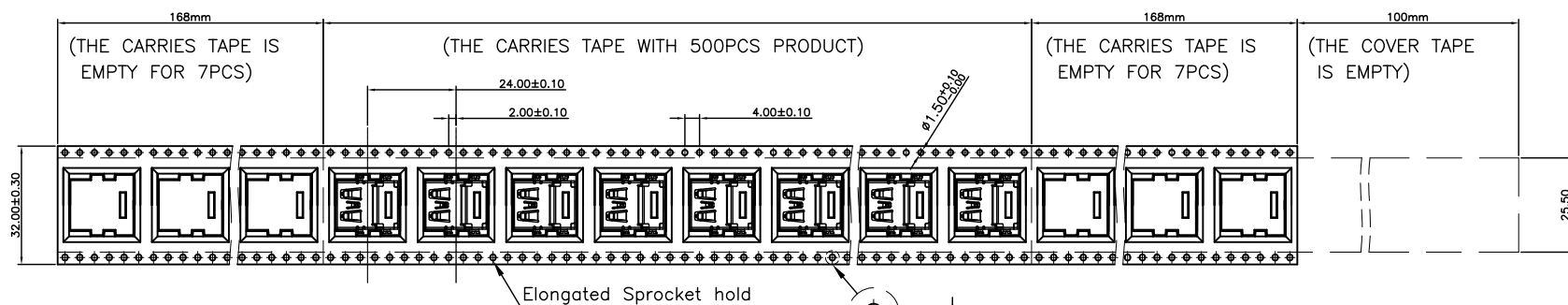
TOLERANCE: ± 0.05 ,
RECOMMENDED PCB LAYOUT
(TOP VIEW)

PIN NO.	1	2	3	4	
SIGNAL NAME	VBUS	D-	D+	PGND	
REMARK	USB 2.0 CONTACT PIN				
PIN NO.	5	6	7	8	9
SIGNAL NAME	SSRX-	SSRX+	GND	SSTX-	SSTX
REMARK	USB 3.0 CONTACT PIN				



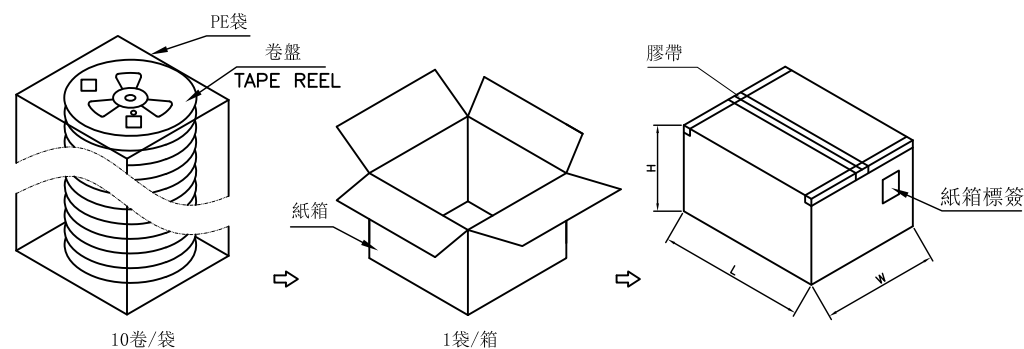
深圳市华宇创精密电子有限公司

TOLERANCE: X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X' $\pm 2'$ X.X' $\pm 0.5'$	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: USB 3.0 AF 沉板反向DIP 斜口 CH=0.8
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC171-USBA09-080-XXB
	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.
UNIT: mm [inch] SCALE:1:1 SIZE: A4			DRAW NO: HYC-2511171524
			SHEET NO. 1 OF 1



備注:

1. 防止漏裝，禁止碰歪產品錫腳。
2. 產品在CARRY TPAE中的方向須如圖所示。
3. COVER剝離力：0.1~0.7N.
4. 剝離角度為：165度~180度。
5. 剝離速度為：300mm/miunies.



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2" X.X" ±0.5" UNIT: mm [inch] SCALE:1:1 SIZE: A4	DRAWN BY :	DATE :	PART NAME:	
	陈一鸣	2014-02-23	包装图	
	CHECKED BY:	DATE :	PART NO.	
	马跃	2014-02-23	MOLD NO.	
APPROVED BY: 邱敏	DATE :	DRAW NO:		
	2014-02-23	SHEET NO.	1 OF 1	